

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Norio KIMURA et al. :
Serial No. NEW : **Attn: Application Branch**
Filed May 25, 2001 : **Attorney Docket No. 2001-0660A**

SUBSTRATE POLISHING APPARATUS
AND SUBSTRATE POLISHING METHOD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,
Washington, DC 20231

Sir:

Prior to examination of the above-referenced U.S. patent application please amend the application as follows:

IN THE CLAIMS

Please amend the claim as follows:

3. (Amended) A substrate polishing apparatus according to claim 1, further comprising dressing means for dressing said polishing surface of said polishing table or cleaning means for cleaning said polishing surface of said polishing table, and wherein said control mechanism controls said dressing means or said cleaning means between the polishing processes to effect the dressing or the cleaning of said polishing surface of said polishing table.

Please add the following new claim:

13. A substrate polishing apparatus according to claim 2, further comprising dressing means for dressing said polishing surface of said polishing table or cleaning means for cleaning

said polishing surface of said polishing table, and wherein said control mechanism controls said dressing means or said cleaning means between the polishing processes to effect the dressing or the cleaning of said polishing surface of said polishing table.

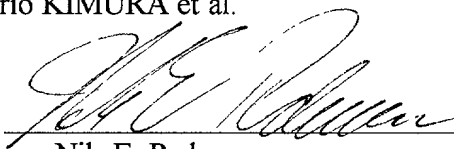
REMARKS

The present Preliminary Amendment is submitted to delete the multiple dependency of the claims, thereby placing such claims in condition for examination and reducing the required PTO filing fee.

Attached hereto is a marked-up version of the changes made to the claim by the current Preliminary Amendment. The attached page is captioned "Version With Markings to Show Changes Made".

Respectfully submitted,

Norio KIMURA et al.

By 

Nils E. Pedersen
Registration No. 33,145
Attorney for Applicants

NEP/krl
Washington, D.C. 20006-1021
Telephone (202) 721-8200
Facsimile (202) 721-8250
May 25, 2001

THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975

Version with Markings to
Show Changes Made

detected by said film thickness detecting means.

3. A substrate polishing apparatus according to claim 1 [or 2], further comprising dressing means for dressing said polishing surface of said polishing table or cleaning means for cleaning said polishing surface of said polishing table, and wherein said control mechanism controls said dressing means or said cleaning means between the polishing processes to effect the dressing or the cleaning of said polishing surface of said polishing table.

4. A substrate polishing method in which a semiconductor substrate held by a top ring is pressed against a polishing surface of a polishing table and a surface to be polished of the semiconductor substrate is polished by a relative movement between the semiconductor substrate and said polishing surface, wherein:

the semiconductor substrate is polished on the same polishing table through plural polishing processes while changing an pressing force for pressing the semiconductor substrate and the number of revolutions of said top ring and/or said polishing table.

5. A substrate polishing method according to claim 4, wherein, when said plural polishing processes are performed, the polishing is effected while adding polishing liquid and/or reagent liquid having having pH at the same side as pH 7.

6. A substrate polishing method according to claim 4, wherein, when said plural polishing processes are performed, the polishing is effected by using same abrasive